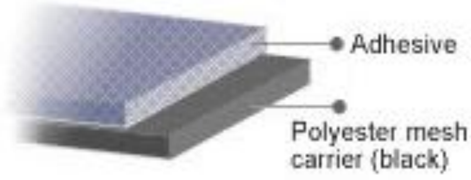
Technical Data Sheet

Dustproof nets with adhesives SP7600HF

Features

- ■ Compared with the pressure sensitive adhesive tape, process reduction is possible because the heat activated adhesive is pre-coated on mesh.
- ■ Compared with the spray method, there is little unevenness of adhesive. SP7600 contributes to quality improvement.
- ■ Since the adhesive layer is applied in opening structure on all over the polyester mesh by our special method, it offers good sound transmission.
- ■ Halogen is not used in the heat activated adhesive and carrier.
（This product is halogen free type of SP7600-P.）

Structure



Main component	Special resin
Carrier	95μm Polyester mesh
Color	Black
Adhesive thickness (μm)	About 170
Release paper thickness (μm)	—
Bonding strength (N/20mm)*	11
St'd size (width × length)	500mm × 100m

* 180° peeling strength (Substrate: PS)

Suitable use

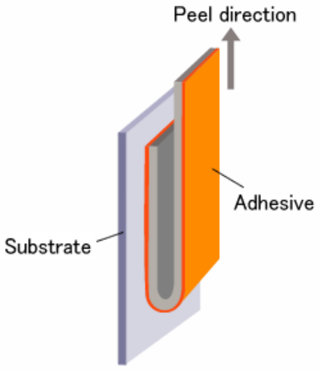
- ■ Ideal for dust-proofing and screening of the opening of speaker front panels (ABS, PS, Aluminum etc.) .

Technical data

1. Bonding strength on various type of substrate (180° peeling strength)

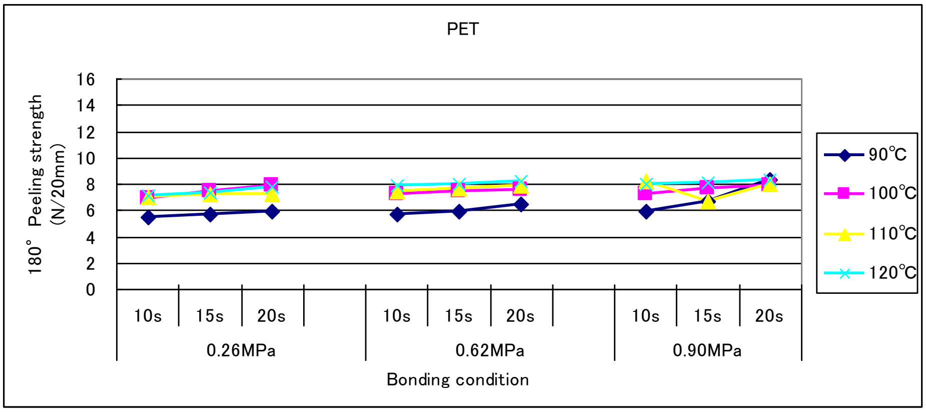
＜Test piece condition＞
Substrate: PC/ABS, PS, PET, PC, PMMA
Bonding area：25×50mm
Bonding condition: temperature: 90℃ to 120℃,
Pressure: 0.26 to 0.90MPa, time: 10 to 20sec
Measuring condition: 23℃±5℃ 60%±20%RH
Peeling speed: 300mm/min
[Left at RT for one hour before measurement]

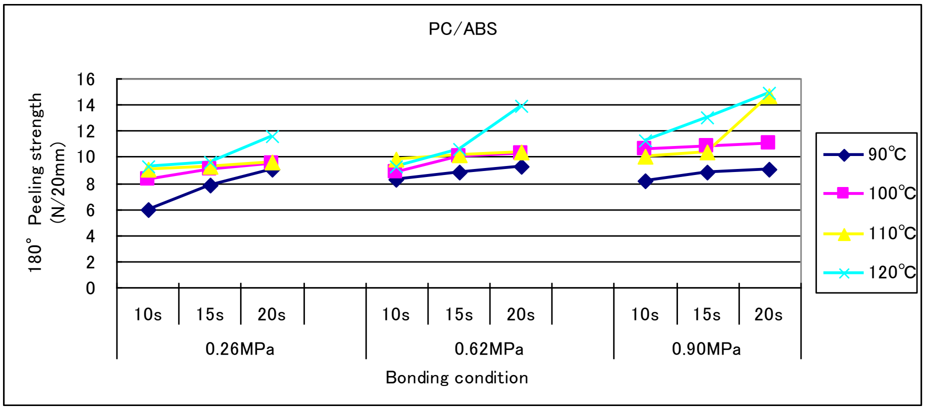
＊ 180° peeling strength into 20mm width.

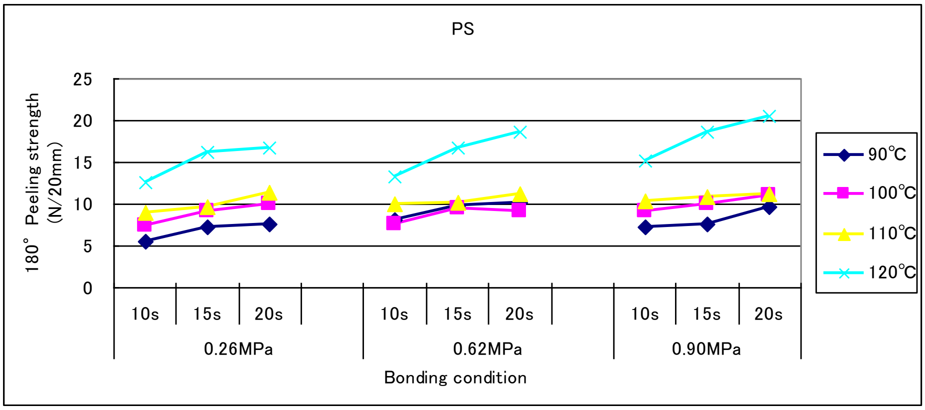


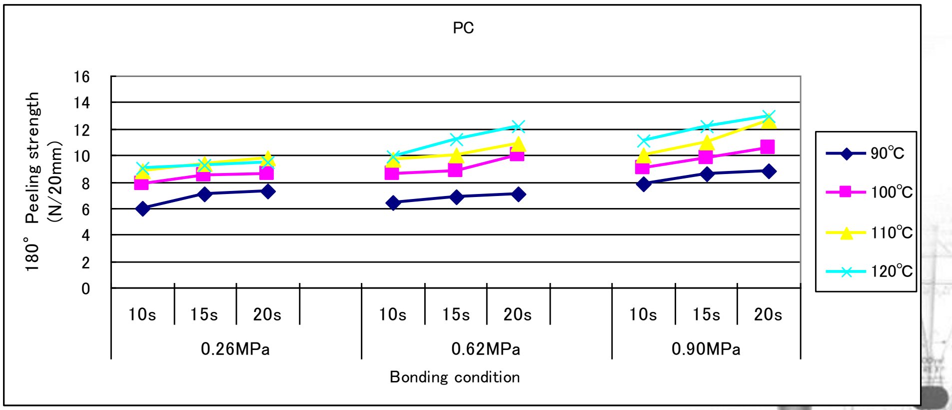
＜180° peeling strength test＞

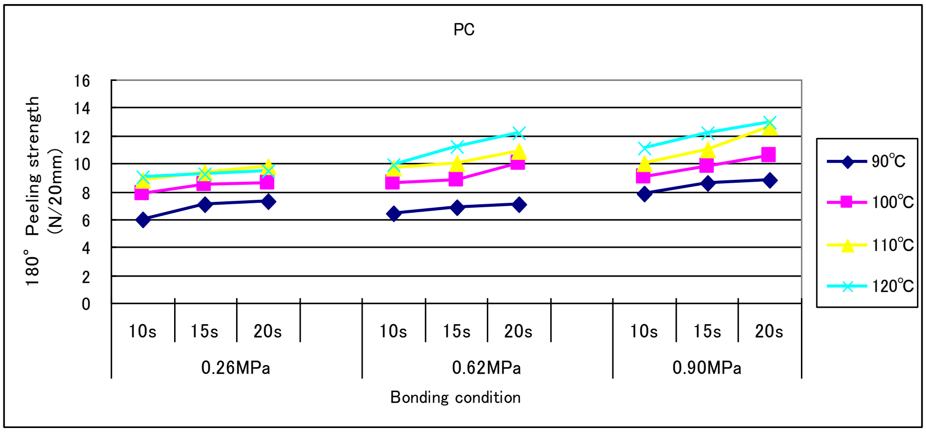
＜Results＞


PET
180° Peeling strength (N/20mm)
16
14
12
10
8
6
4
2
0
10s
15s
20s
0.26MPa
0.62MPa
0.90MPa
Bonding condition
90℃
100℃
110℃
120℃


PC/ABS
180° Peeling strength (N/20mm)
16
14
12
10
8
6
4
2
0
10s
15s
20s
0.26MPa
0.62MPa
0.90MPa
Bonding condition
90℃
100℃
110℃
120℃


PS
180° Peeling strength (N/20mm)
25
20
15
10
5
0
10s
15s
20s
0.26MPa
0.62MPa
0.90MPa
Bonding condition
90℃
100℃
110℃
120℃


PC
180° Peeling strength (N/20mm)
16
14
12
10
8
6
4
2
0
10s
15s
20s
0.26MPa
0.62MPa
0.90MPa
Bonding condition
90℃
100℃
110℃
120℃



Substrate：PET (N/20mm)

		90℃	100℃	110℃	120℃
0.26MPa	10s	5.49	6.87	7.06	7.16
	15s	5.69	7.46	7.26	7.36
	20s	5.89	7.85	7.26	7.81
0.62MPa	10s	5.69	7.26	7.46	7.85
	15s	5.89	7.46	7.65	8.04
	20s	6.47	7.55	7.85	8.24
0.90MPa	10s	5.89	7.26	8.24	8.04
	15s	6.67	7.65	6.67	8.14
	20s	8.34	7.85	8.04	8.34

Substrate：PC (N/20mm)

		90℃	100℃	110℃	120℃
0.26MPa	10s	5.98	7.87	8.87	9.06
	15s	7.06	8.46	9.36	9.24
	20s	7.26	8.65	9.85	9.44
0.62MPa	10s	6.47	8.55	9.65	9.95
	15s	6.87	8.85	10.04	11.24
	20s	7.06	10.04	10.83	12.22
0.90MPa	10s	7.85	9.04	10.04	11.14
	15s	8.63	9.81	11.03	12.22
	20s	8.83	10.52	12.61	12.99

Substrate：PC/ABS (N/20mm)

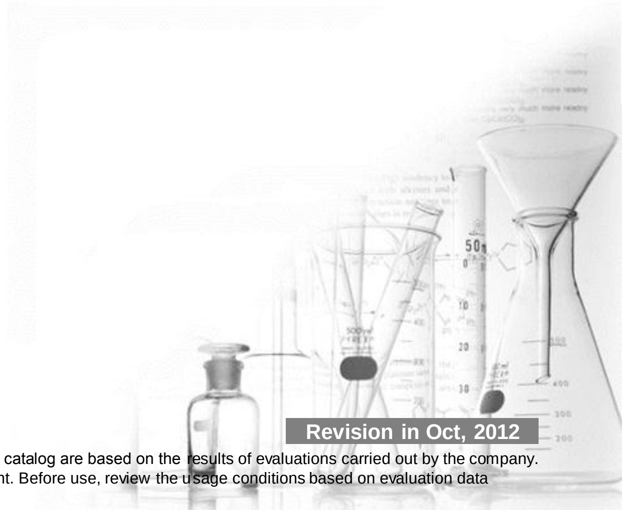
		90℃	100℃	110℃	120℃
0.26MPa	10s	5.98	8.24	9.03	9.22
	15s	7.85	9.04	9.32	9.61
	20s	9.03	9.44	9.61	11.58
0.62MPa	10s	8.24	8.85	9.83	9.32
	15s	8.87	10.03	10.12	10.59
	20s	9.24	10.22	10.32	13.93
0.90MPa	10s	8.18	10.59	10.03	11.28
	15s	8.87	10.79	10.42	12.97
	20s	9.06	10.99	14.72	14.91

Substrate：PMMA (N/20mm)

		90℃	100℃	110℃	120℃
0.26MPa	10s	5.20	6.18	7.65	8.04
	15s	6.08	7.26	8.24	8.44
	20s	8.04	8.83	9.03	9.03
0.62MPa	10s	7.65	8.04	8.24	8.44
	15s	8.24	8.44	8.83	9.03
	20s	9.61	9.22	8.42	10.59
0.90MPa	10s	7.85	8.63	9.03	9.03
	15s	8.24	9.61	9.61	9.81
	20s	9.61	10.79	10.99	10.79

Substrate：PS (N/20mm)

		90℃	100℃	110℃	120℃
0.26MPa	10s	5.49	7.46	9.03	12.56
	15s	7.26	9.22	9.61	16.28
	20s	7.65	10.01	11.38	16.68
0.62MPa	10s	8.04	7.65	10.01	13.24
	15s	9.81	9.42	10.20	16.68
	20s	10.20	9.22	11.18	18.64
0.90MPa	10s	7.26	9.22	10.40	15.21
	15s	7.65	10.01	10.79	18.64
	20s	9.61	10.99	11.28	20.60



Revision in Oct, 2012